

# Electrode erosion and lifetime performance of a compact and repetitively triggered field distortion spark gap switch

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**Abstract**—Electrode erosion and lifetime performance of a compact and repetitively triggered field distortion spark gap switch was studied at a repetitive frequency rate of 30 Hz, a peak current of 8.5 kA, and working voltage of  $\pm 35$  kV when the switch was filled with a gas mixture 30% SF<sub>6</sub> and 70% N<sub>2</sub> at a pressure of 0.3 MPa. The variation of the time-delay jitter and self-breakdown voltage were both studied for the whole service lifetime of the spark gap switch. The morphology of both the electrodes and the plate insulator, before and after the service lifetime tests, is also analyzed. The results show that during these tests, the time-delay jitter is basically synchronized with the self-breakdown voltage jitter, and both undergo firstly a process of rapidly decreasing their values, then remain stable and finally and gradually increase after 70,000 pulses. The change of the electrode surface roughness (i.e. the surface profile), caused by erosion and chemical deposits in the switch cavity, are mainly the two factors that affect the time-delay jitter of the switch. Tip protrusions on the electrode surface, due to electrode erosion, contribute to reducing the time-delay jitter. However, due to chemical reactions, fluorides and sulfides are deposited on the switch components, as well as metal particles caused by electrode erosion sputtering. Slowly, after a large number of shots, all these phenomena affect the self-breakdown performance resulting in an increased self-breakdown voltage jitter, which also causes the time-delay jitter to increase. Although there are a number of reasons that contribute to the performance of the switch to deteriorate it is fortunate that if a switch suffering a degraded performance is reassembled, with the electrodes mechanically polished and all the components cleaned, the optimal performance of the switch can be restored. If maintenance work is carried out regularly to preserve the condition of the switch inner components, the service lifetime of the switch can be prolonged.

**Index Terms**—electrode erosion, service lifetime, time-delay jitter, self-breakdown voltage, micromorphology, field-distortion switch

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## I. INTRODUCTION

Due to their excellent features such as high-voltage, high-current, low inductance, and low time-delay jitter, spark-gap switches are widely used in various practical applications such as particle accelerators [1], linear transformer drivers [2-3], and repetitive electron beam sources [4-5]. Recent developments in the design of repetitive pulsed power sources require spark gap switches capable of driving high-current with a low time-delay jitter ( $< 5$  ns) and operated at a high repetition rate for a very large number of shots [6-10]. For these applications, the field-distortion switch is the optimum choice.

The performance of a spark gap switch typically deteriorates as the operational time increases. The lifetime is determined by electrode erosion, gas decomposition and disassociation and insulation damage that occurs as energy is dissipated in the switch [11]. Electrode erosion plays an important role in the many impact factors on the lifetime of the switch. Extensive research has been performed on the electrode erosion in gas switches [12-19]. Electrode erosion occurs when the electrode material is permanently removed from the electrode surface and could be considered a result of the interaction between the electrode and the arc plasma. Unfortunately, since the operating conditions vary widely from a switch design to another, there is no precise method for describing the erosion process or predicting a switch life expectancy. A systematic experimental research on electrode erosion with different electrode materials and pulse parameters have been published [20], as well as models to estimate the electrode erosion [21]. Although many researchers studied the erosion characteristics of the electrodes and evaluated the lifetime characteristics of the switches, to the authors' best knowledge, no publication covers either the processes that make the time-delay jitter and self-breakdown voltage jitter

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vary with the lifetime, or on how and when to carry out appropriate maintenance work. This paper reports on studies of electrode erosion and lifetime performance of a compact and repetitively triggered field distortion spark gap switch. The main factors affecting the performance of the switch are analyzed and a schedule for preventive maintenance work is suggested to provide the basis for further prolonging the service lifetime of a spark-gap switch.

## II. EXPERIMENTAL ARRANGEMENT

A compact three-electrode field-distortion spark gap switch was used, which includes two main electrodes, two plate insulators of Polymethyl methacrylate (PMMA), a disk-like trigger electrode, two pairs of O-ring seals and sixteen nylon screws for fastening. The main electrodes and trigger electrode are made of 316L stainless steel. The switch has a small size (OD  $\times$  height) of only 150 mm  $\times$  42 mm, a light weight of about 1.5 kg, can withstand a high voltage in excess of 110 kV. Fig. 1 provides a schematic overview of the experimental arrangement used in the present studies. This paper is a follow-on of [22], with the technical details and experimental arrangement being fully described therein.

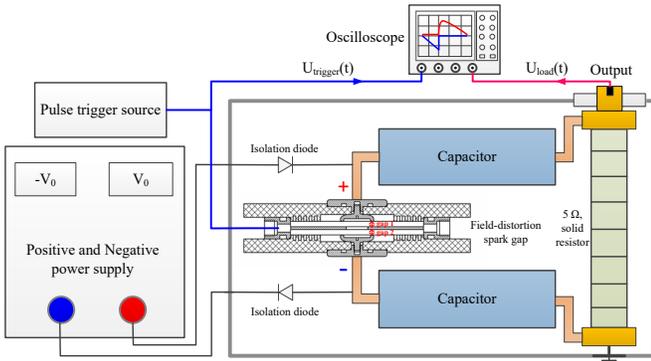


Fig. 1. Schematic of the experimental arrangement used in the present studies.

## III. Experimental results and discussion

### A. Degradation of switch performance

Time-delay jitter is an important parameter in describing the quality of synchronization between switches operated in parallel and can greatly influence the rise time of the final output current of the system: a too large value will slow down the energy transfer rate. The self-breakdown of the switch refers to the phenomena that occur when the applied voltage exceeds the maximum withstand voltage. The self-breakdown voltage affects the operating voltage range, which is an important parameter for a triggered switch. To study the performance degradation of the present switch, the time-delay jitter and the self-breakdown voltage were both measured during the lifetime tests, as shown in Fig. 2. For these tests, a new switch was used, which was filled with the SF<sub>6</sub>-N<sub>2</sub> gas mixture at a pressure of 0.3 MPa, the applied voltage was  $\pm 35$  kV, and the current was 8.5 kA, and a trigger pulse with a voltage time rate-of-change of 0.25 kV/ns was used. Due to residual burrs and incompletely cleaned stains remaining on the surface of the electrodes after they were manufactured, the breakdown voltage varied greatly during the first 100 shots of switch ‘forming’, so the operation

frequency was set to 1Hz during this preliminary part of the test. After forming, the switch was operated at a repetition-rate of 30 Hz, since it was demonstrated that the optimum repetition frequency that minimizes the time-delay jitter is in a range between 20 Hz and 30 Hz, when the spark gap is filled with a gas mixture of 30% SF<sub>6</sub> and 70% N<sub>2</sub> [24].

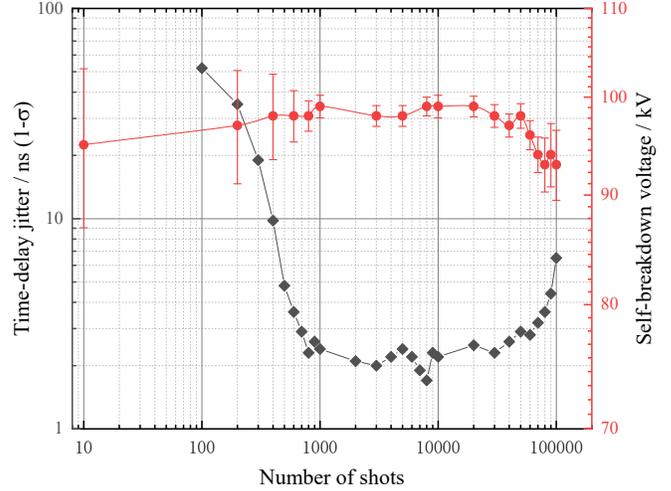
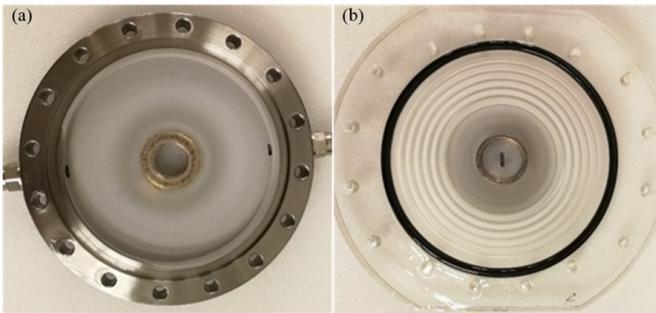


Fig. 2. Time-delay jitter and self-breakdown voltage versus the number of pulse shots for a new switch.

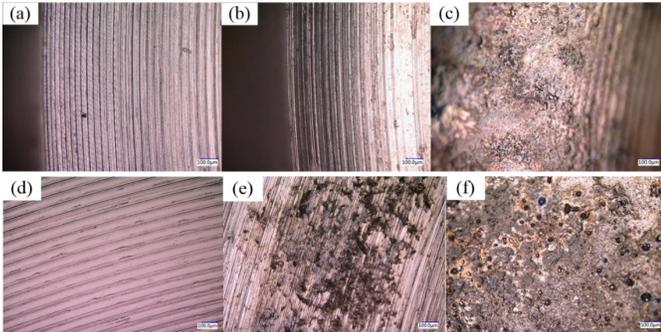
Tests results show that the time-delay jitter is rapidly reduced within the first 700 shots. For the next 60,000 shots, the time-delay jitter is practically stable having values between 1.7 ns and 3.0 ns. However, from about 70,000 shots to 100,000 shots, the time-delay jitter increases from 3.2 ns to 6.5 ns. The self-breakdown voltage jitter also appears to be a process that initially decrease rapidly before remaining stable for the long lifetime of about 70000 shots after which it is gradually degrading, in a similar way as the time-delay jitter. When the time-delay jitter is large, the self-breakdown voltage jitter is also large. When the time-delay jitter is low, the self-breakdown voltage jitter is also relatively small. The reasons for this phenomenon are related to the electrode erosion and the chemical composition within the switch resulting from the gas discharge, both of which are discussed in detail below.

### B. The complex phenomena of electrode erosion and their influence on the switch lifetime

Fig. 3 presents photographs of the main switch components: the trigger electrode, the plate insulator and the main electrode, after 100,000 shots. It can be seen that an annular erosion region is formed on the trigger electrode, with a diameter similar to that of the main electrode. This annular region is evenly eroded, which is an important indication suggesting a stable operation. However, there are many tiny cracks, pits and bumps on both the main electrode and the trigger electrode surface and also a layer of white powder attached to the surfaces of both the electrode and the plate insulator. The appearance of all these unwanted phenomena may provide the explanation of why the time-delay jitter gradually increases after 70,000 shots. In order to fully understand the nature of these phenomena, the microstructure of the main electrode and the trigger electrode were all analyzed before, during and after the tests, with the main results presented in Fig. 4.

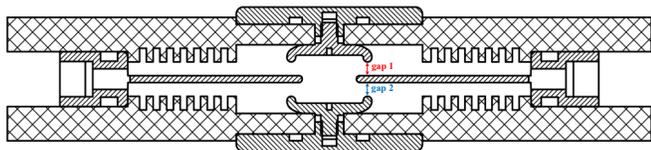


**Fig. 3.** Photographs of certain switch components after 100,000 shots. (a) trigger electrode and (b) plate insulator and the main electrode.



**Fig. 4.** The change in the micromorphology of the main and the trigger electrode from 0 shots to 100,000 shots. (a) initial state of the main electrode surface. (b) main electrode surface after 1,000 shots. (c) main electrode surface after 100,000 shots. (d) initial state of the trigger electrode surface. (e) trigger electrode surface after 1,000 shots. (f) trigger electrode surface after 100,000 shots.

The time-delay jitter degradation due to the electrode profile change caused by erosion can be explained by the comparison of the micromorphology of the electrodes when tested at different number of pulse shots, as shown in Fig. 4. After 1000-shot tests, the surface of the trigger electrode opposite to the positive electrode became rough with a large number of tip protrusions (see Fig. 4(e)), which promoted the generation of initial electrons and facilitated breakdown of the switch, resulting in much lower time delay jitter. This explanation is supported by other published works [25, 26].



**Fig. 5.** Schematic of the three-electrode spark gap switch used in the present studies.

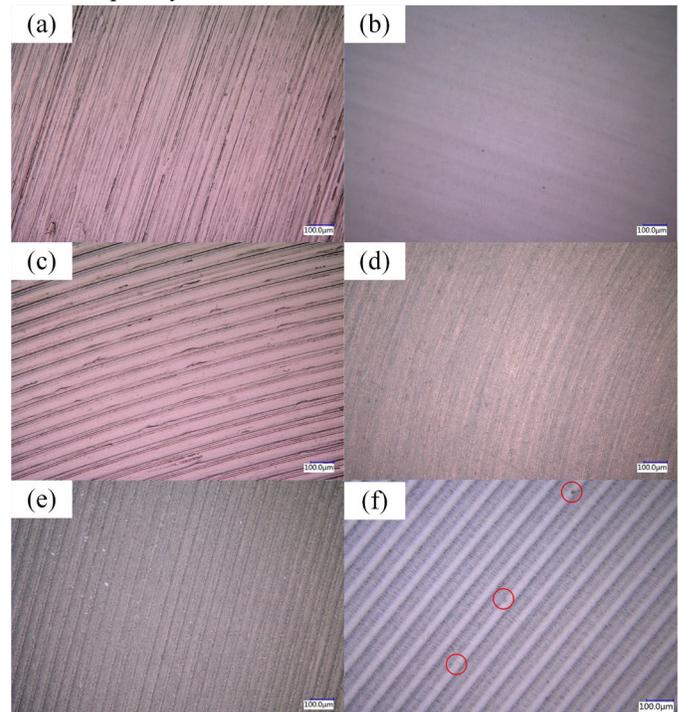
Due to the presence of the disk-like trigger electrode, the space between the two electrodes of the switch described in this paper is divided into two equal parts: ‘gap 1’ and ‘gap 2’, as shown in Fig. 5. Gap 1 represents the triggered gap while gap 2 is the self-breakdown gap. Results presented in [24], show that, for a trigger pulse having a voltage/time rate-of-change 0.25 kV/ns and when the working coefficient of the switch exceeds 0.7, the time-delay jitter is dominated by gap 1, **where the working coefficient is the ratio of operating voltage to self-breakdown voltage**. The presence of tip protrusions on the trigger or main electrode is beneficial to reducing the time-delay jitter of gap 1. However, as the number of test shots increases, the protrusions on the surface of the electrode become relatively uniform and smooth under the constant erosion and **melting due to**

**arc discharge** (see Fig. 4(f)). As described earlier, when the number of test shots is greater than 70,000, the time-delay jitter of the switch starts to gradually increase with the shot number, which indicates the electrode surface erosion gradually became uniform and smooth.

Experimental results show that moderate erosion of the electrodes is beneficial in reducing the time-delay jitter of the switch, but excessive erosion increases the time-delay jitter. It can be predicted that there is an optimum electrode surface profile that minimizes the time-delay jitter.

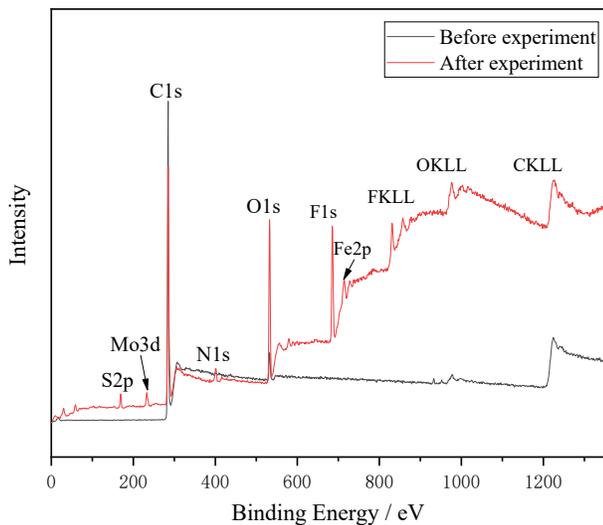
### C. Element Spectrum Analysis

As evident in Fig. 6, a layer of white powder covers the surfaces of the main electrodes, the trigger electrode and the plate insulator. The chemical composition of this powder was analyzed using X-ray photoelectron spectroscopy (XPS) before and after tests, with the main results presented in Fig. 7 and Fig. 8. It can be seen from Fig. 7 that peaks of elements such as S, N and F are clearly present when the surface of the insulator is analyzed after a large number of high-frequency operations. The F element is also detected in the white powder on the surface outside the discharge region of the trigger electrode, as shown in Fig. 8. Further analysis indicates that gases, such as CO<sub>2</sub>, CO, CF<sub>4</sub> and H<sub>2</sub>S were also generated during the discharges. An unexpected, but very important finding is the presence of metallic elements such as Fe and Mo on the surface of the insulator, which may cause its insulation performance to deteriorate quickly.

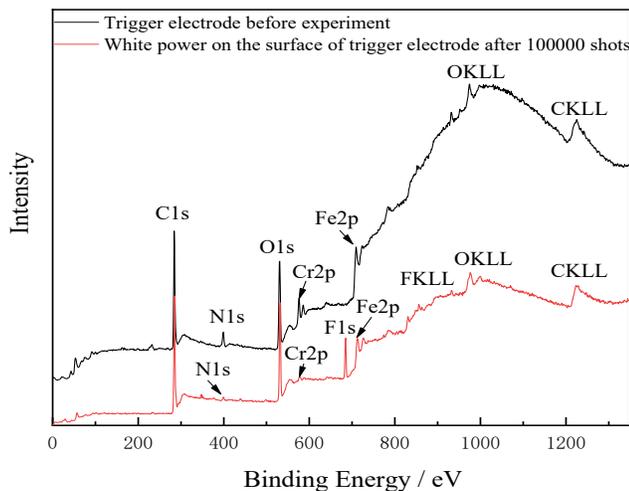


**Fig. 6.** Change in the micromorphology of various switch components from 0 shots to 100,000 shots. (a) initial state of the trigger electrode surface outside of the discharge area. (b) the trigger electrode surface outside of the discharge area after 100,000 shots. (c) initial state within the main electrode. (d) the surface within the main electrode after 100,000 shots. (e) initial state of the first annular surface on the plate insulator. (f) the first annular surface on the plate insulator after 100,000 shots; the position of a few metallic micro particles adhered to the insulator surface is highlighted using circles.

On the surface of the plate insulator there are some 10 μm-sized sputtered metal spots, as seen in Fig. 6(f), which proves



**Fig. 7.** The full XPS spectrum of the white powder present on the plate PMMA insulator surface after 100,000 shots, compared with the initial spectrum obtained before the tests.



**Fig. 8.** The full XPS spectrum of the white powder present on the trigger electrode surface outside the discharge area after 100,000 shots compared with the initial spectrum obtained before the tests.

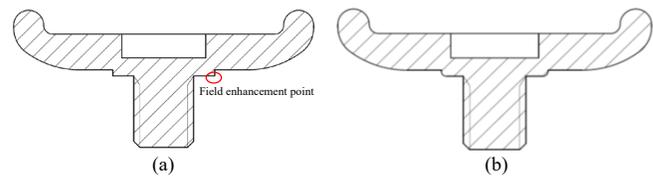
that melted electrode material near the electric arc spot was ejected during the high frequency operation. These metallic micro particles adhered to the surface of the plate insulator, obviously decreasing its insulation properties and leading to an overall reduction in the lifetime of the switch.

The presence of fluorides, sulfides and metal particles inside the switch cavity after a certain number of shots can also affect the discharge performance, causing the time-delay jitter to gradually increase and the insulation performance to deteriorate.

#### D. Partial discharge and its influence on the switch lifetime

In addition to electrode erosion, another important factor that affects the lifetime of the switch is the partial discharge, which can create localized breakdown and permanent damage to the insulating material. As the number of pulse discharges increases, the breakdown of the insulating material caused by partial discharge will gradually expand, eventually leading to complete body-breakdown, resulting in failure of insulation performance and preventing the switch from working.

For the compact field-distortion spark gap switch described in this paper, the triple-point of the high-voltage main electrode, the insulating gas, and the plate insulator is the place where the partial discharge is most likely to occur, so it is necessary to minimize the electric field strength by careful design. The main electrode shown in Fig. 9(a) has a sharp edge which greatly enhances the electric field strength. As shown in Fig. 9(a), after 100,000 shots tests with this main electrode design, the plate insulator had obvious dendritic breakdown marks as presented in Fig. 10. This damage is critical and cannot be recovered, thus affecting the service lifetime of the switch. This phenomenon can be however avoided if the sharp edge of the electrode is rounded as presented in Fig. 9(b). A careful structural design to avoid partial discharges is therefore important for improving the lifetime of the switch.



**Fig. 9.** The main electrode of the switch before and after the sharp edge was rounded.



**Fig. 10.** Photo of a plate insulator after 100,000 shots test using the main electrode with sharp edge.

#### E. Switch performance recovery

To further understand the specific reasons for the observed deterioration in the switching performance after 100,000 shots of the lifetime tests, the switch was disassembled and an ultrasonic cleaner was used to clear all attachments from the surfaces of the main electrodes, trigger electrode and plate insulators. After that, the following five experiments were conducted for different component combinations of the switch, as shown in Table I.

Switch I. The main and trigger electrodes are brand new; The plate insulators are old but cleaned.

Switch II. The main and trigger electrodes are old and cleaned, but the plate insulators are brand new.

Switch III. The main electrodes, trigger electrode and plate insulators are all old and cleaned.

Switch IV. The main and trigger electrodes are old but had been mechanically polished and cleaned. The plate insulators are also old but cleaned.

Tab. I. Comparison of five different component combinations of the switch

	Switch I		Switch II		Switch III		Switch IV		Switch V		Switch 0
components	Main electrodes	new	Main electrodes	old, cleaned	Main electrodes	old, cleaned	Main electrodes	old, cleaned, polished	Main electrodes	old, cleaned, polished	Final state after 100,000 shot tests.
	Trigger electrode	new	Trigger electrode	old, cleaned	Trigger electrode	old, cleaned	Trigger electrode	old, cleaned, polished	Trigger electrode	old, cleaned, polished	
	Plate insulators	old, cleaned	Plate insulators	new	Plate insulators	old, cleaned	Plate insulators	old, cleaned	Plate insulators	new	
"forming" shots	1000		1000		1000		1000		1000		---
average delay time	170 ns		183 ns		181 ns		186 ns		189 ns		178 ns
time-delay jitter	2.4 ns		4.5 ns		4.7 ns		2.7 ns		2.8 ns		6.5 ns

Switch V. The main and trigger electrodes are old but had been mechanically polished and cleaned. The plate insulators are brand new.

Switch 0. The final state after 100,000-shot tests.

As the data in Table I shows, if new main and trigger electrodes are used in reassembling the switch with old but cleaned insulators (Switch I), the switch has the essentially the same time-delay jitter (~2.4 ns) as the new one (used in Fig. 1). After cleaning the attachments inside the switch, the time-delay jitter is reduced from 6.5 ns (Switch 0) to 4.7 ns (Switch III). Compared to Switch III, by replacing new plate insulators, the time-delay jitter of Switch II (4.5 ns) is not changed. Within the allowed deviation range, the time-delay jitters of Switch II and Switch III are considered to be practically the same. However, when the main electrodes and the trigger electrode of the switch were mechanically polished and cleaned, the time-delay jitter is further reduced to 2.7 ns (Switch IV). Compared to Switch IV, the time-delay jitter of Switch V (2.8 ns) is not changed by replacing new plate insulators.

The experimental results of Switch II and Switch III show that if only the chemical deposits caused by the discharge in the switch cavity are cleaned, the time-delay jitter cannot be restored to the optimal state, which means that the deposits of chemical reaction are a factor affecting the time-delay jitter, but not the only factor.

The experimental results of Switch IV and Switch V show that the surface roughness of the electrode (i.e. the surface profile) has a great influence on the time-delay jitter. After the surface of the electrode is mechanically polished, the surface profiles of the electrodes are substantially the same as that of the new electrode. Therefore, with the component combinations such as Switch IV and Switch V, the time-delay jitter of the switch can be restored to its optimal state.

Fortunately, the experimental results of Switch IV further indicate that if after 100,000 shots of the lifetime tests the main and the trigger electrode of the switch are both mechanically polished and cleaned and then reassembled with the cleaned old plate insulators, the time-delay jitter of the switch can still be restored to its optimal state. This provides an experimental basis for the switch maintenance and recovery.

#### IV. CONCLUSION

In this paper, electrode erosion and lifetime performance of a compact and repetitively triggered field distortion spark gap switch was studied and the main factors affecting the performance of the switch were analyzed in detail. The experimental results show that the electrode surface roughness (i.e. the surface profile) and chemical deposits caused by discharge are two main factors affecting the time-delay jitter of the switch. Fluoride, sulfide and metal particles that are present inside the switch cavity, as well as damage to the insulator due to partial discharge, are also important factors influencing the lifetime of the switch. By optimizing the electrode surface profile design and avoiding partial discharge, the lifetime of the switch insulator can be improved. By periodically carrying work to preserve the state of the switch components, the service lifetime of the switch can be prolonged.

Future plans include increasing the operation lifetime of the switch by using a better erosion-resistant electrode material such as a copper-tungsten alloy and decreasing the time-delay jitter of the switch by optimizing the electrode surface profile in the discharge region.

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